

2SA0683 (2SA683), 2SA0684 (2SA684)

Silicon PNP epitaxial planar type

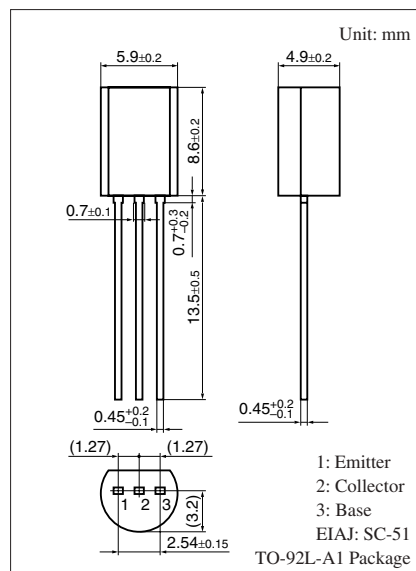
For low-frequency power amplification and driver amplification
Complementary to 2SC1383, 2SC1384

■ Features

- Allowing supply with the radial tapping

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Collector-base voltage (Emitter open)	2SA0683	V_{CBO}	−30	V
	2SA0684		−60	
Collector-emitter voltage (Base open)	2SA0683	V_{CEO}	−25	V
	2SA0684		−50	
Emitter-base voltage (Collector open)		V_{EBO}	−5	V
Collector current		I_{C}	−1	A
Peak collector current		I_{CP}	−1.5	A
Collector power dissipation		P_{C}	1	W
Junction temperature		T_{j}	150	°C
Storage temperature		T_{stg}	−55 to +150	°C



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	2SA0683 2SA0684	V_{CBO} $I_{\text{C}} = -10 \mu\text{A}, I_{\text{E}} = 0$	-30			V
			-60			
Collector-emitter voltage (Base open)	2SA0683 2SA0684	V_{CEO} $I_{\text{C}} = -2 \text{ mA}, I_{\text{B}} = 0$	-25			V
			-50			
Emitter-base voltage (Collector open)	V_{EBO}	$I_{\text{E}} = -10 \mu\text{A}, I_{\text{C}} = 0$	-5			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{\text{CB}} = -20 \text{ V}, I_{\text{E}} = 0$			-0.1	μA
Forward current transfer ratio *1	h_{FE1}^{*2}	$V_{\text{CE}} = -10 \text{ V}, I_{\text{C}} = -500 \text{ mA}$	85		340	—
	h_{FE2}	$V_{\text{CE}} = -5 \text{ V}, I_{\text{C}} = -1 \text{ A}$	50			
Collector-emitter saturation voltage	$V_{\text{CE(sat)}}$	$I_{\text{C}} = -500 \text{ mA}, I_{\text{B}} = -50 \text{ mA}$		-0.2	-0.4	V
Base-emitter saturation voltage	$V_{\text{BE(sat)}}$	$I_{\text{C}} = -500 \text{ mA}, I_{\text{B}} = -50 \text{ mA}$		-0.85	-1.20	V
Transition frequency	f_{T}	$V_{\text{CB}} = -10 \text{ V}, I_{\text{E}} = 50 \text{ mA}, f = 200 \text{ MHz}$		200		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{\text{CB}} = -10 \text{ V}, I_{\text{E}} = 0, f = 1 \text{ MHz}$		20	30	pF

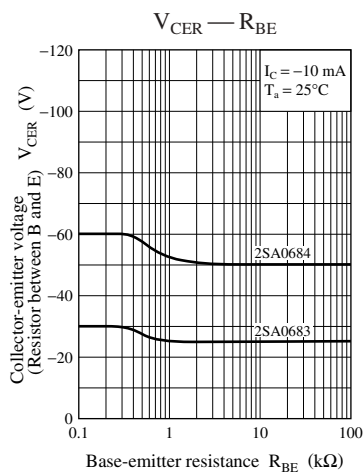
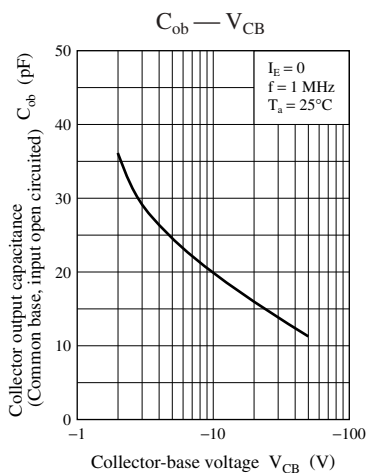
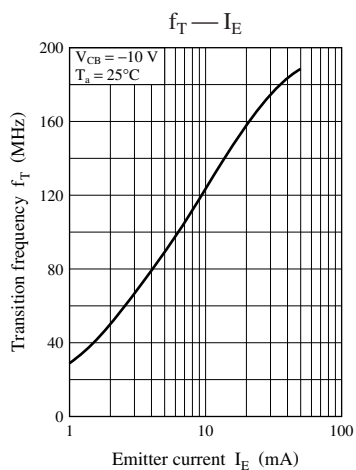
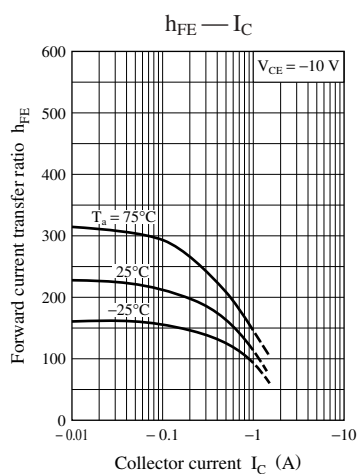
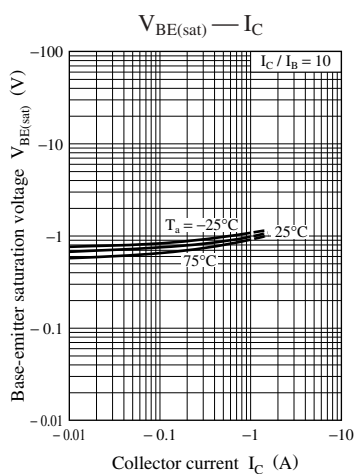
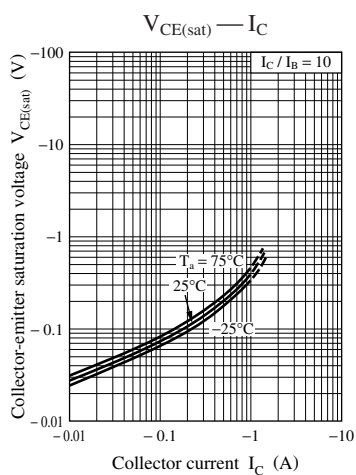
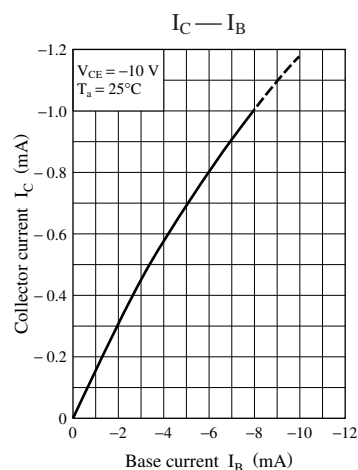
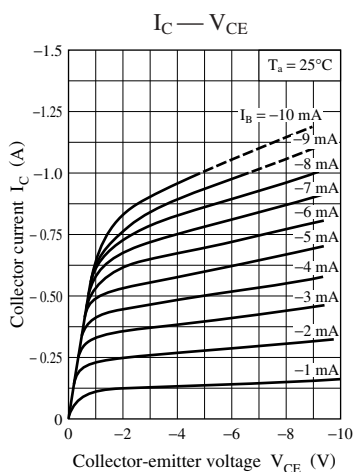
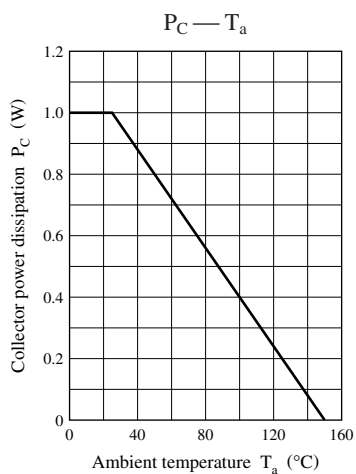
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

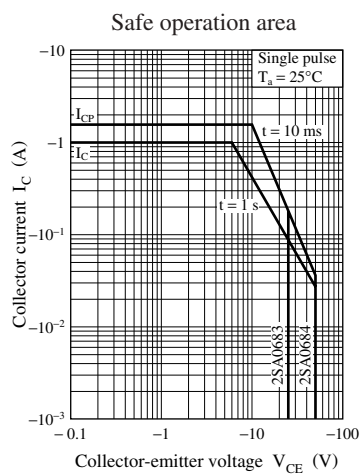
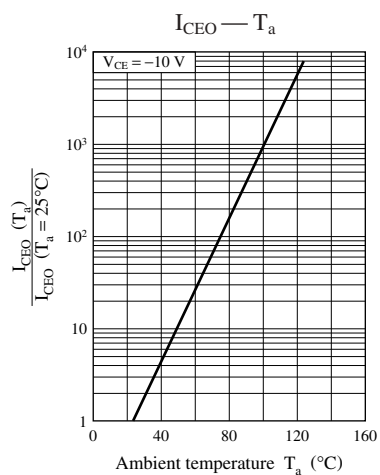
2. *1: Pulse measurement

*2: Rank classification

Rank	Q	R	S
h_{FE}	85 to 170	120 to 240	170 to 340

Note) The part numbers in the parenthesis show conventional part number.





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